

NUMBER 316080

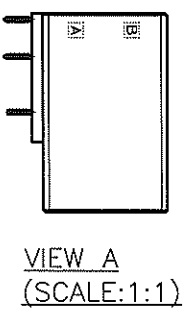
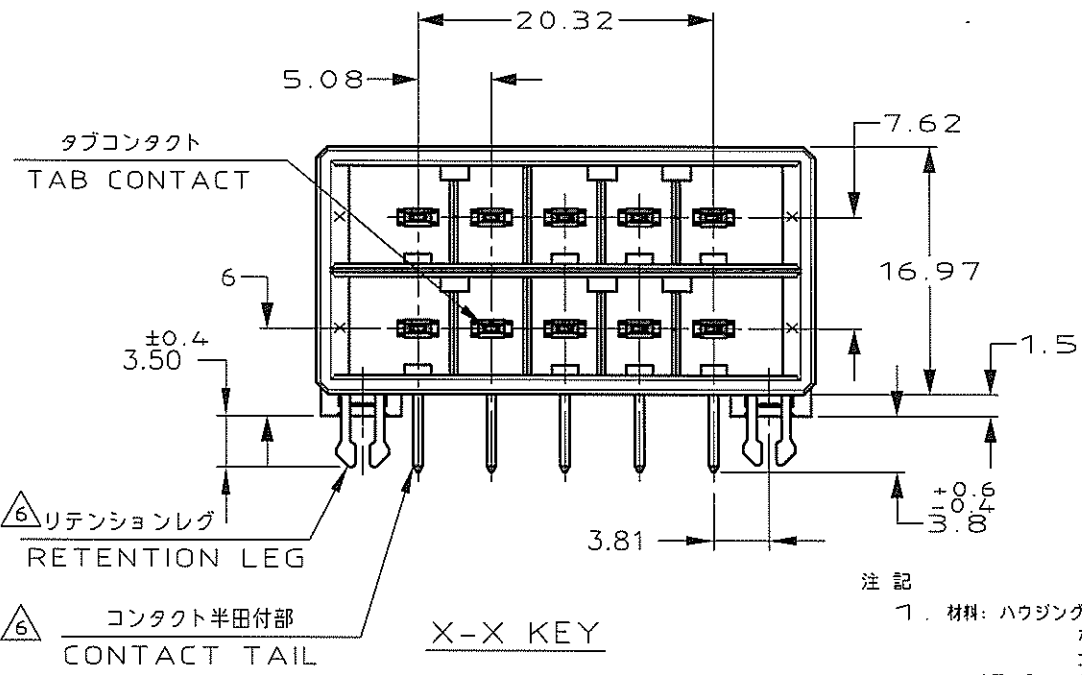
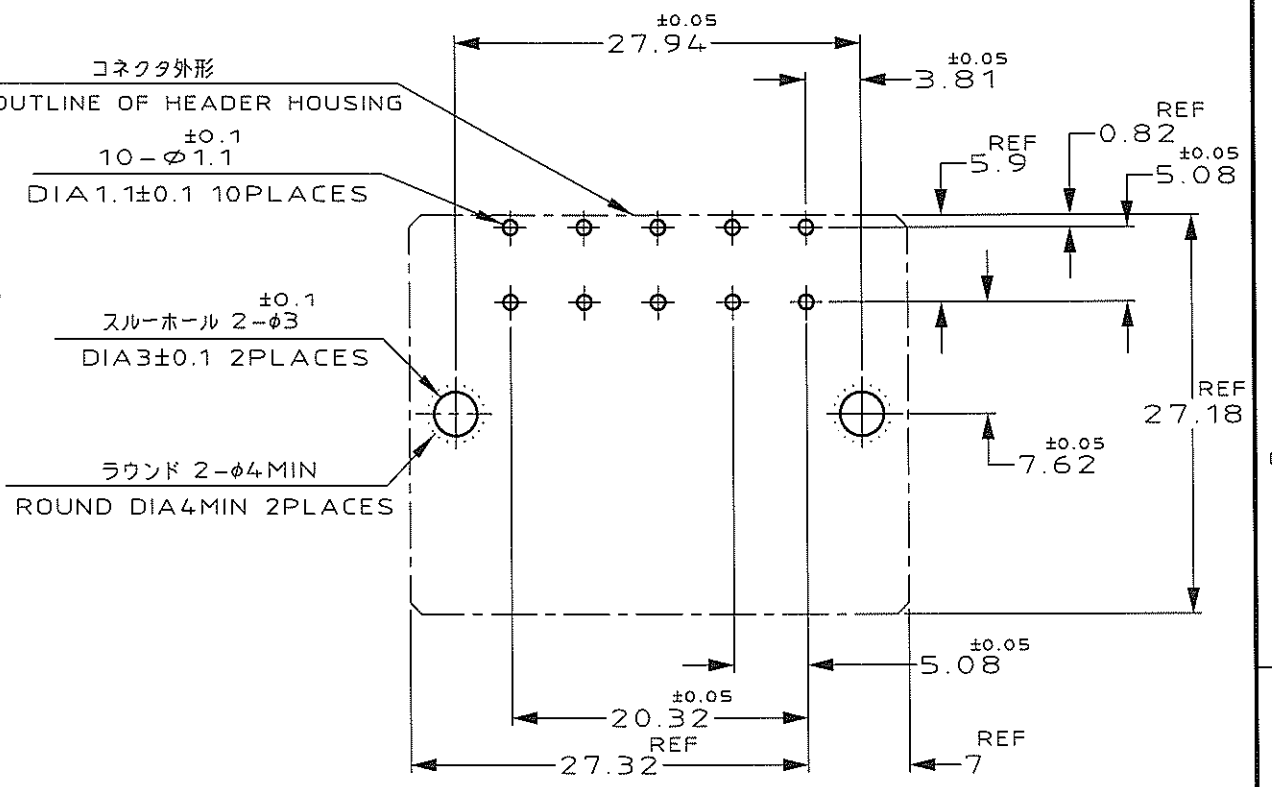
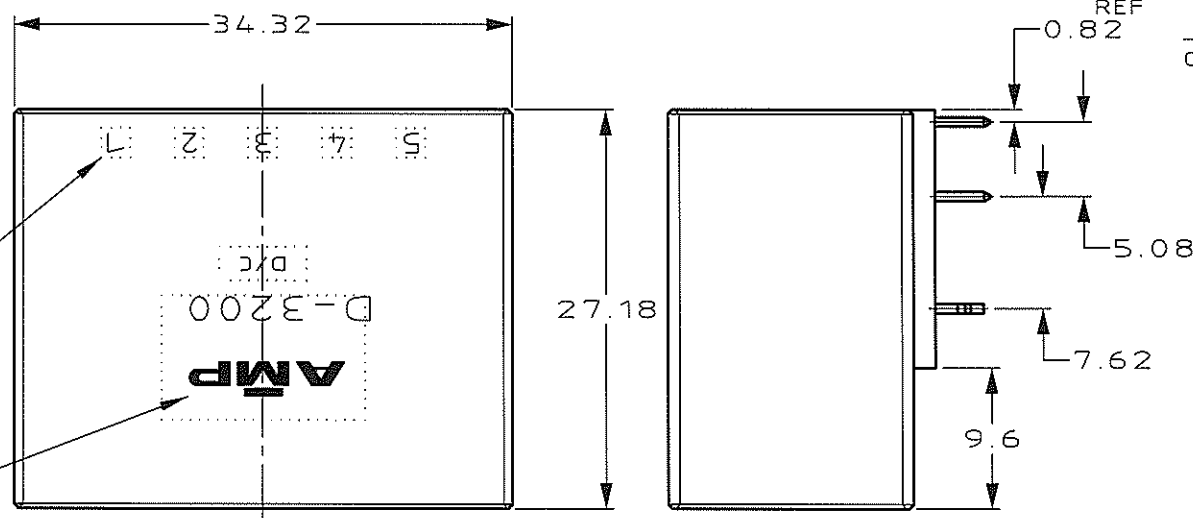
3rd ANGLE PROJECTION

METRIC

DIMENSIONS IN MILLIMETERS. DO NOT SCALE PRINT

PRINT DIST

VIEW A
回路番号
CIRCUIT NO
AMPマーク
シリーズマーク
SERIES MARK



推奨基板取付け穴寸法
PC 基板厚: 1.6±0.1
(非累積公差)
(コネクタ搭載面)

RECOMEND PC BOARD HOLE PATTERN
PC BOARD THICKNESS: 1.6±0.1
(NOT ACCUMULATE TOLERANCE)
(CONNECTOR MOUNT SIDE)

NOTES
1. MATERIAL: HOUSING: GLASS FILLED THERMO PLASTIC, POLYESTER (94V-0), COLOR: BLACK
CONTACT: COPPER ALLOY
RETENTION LEG: COPPER ALLOY
△2. FINISH (CONTACT AREA): 0.38 μm MIN GOLD PLATING OVER Ni PLATING
△3. FINISH (CONTACT AREA): 0.76 μm MIN GOLD PLATING OVER Ni PLATING
△4. FINISH (CONTACT AREA): 2.0 μm MIN PLATED OVER NICKEL
△5. FINISH (RETENTION LEG): TIN LEAD PLATED (CONTACT TAIL)
△6. FINISH (RETENTION LEG): TIN PLATED (CONTACT TAIL)

注記
1. 材料: ハウジング: ガラス入り熱可塑性ポリエステル樹脂 (94V-0), 色: 黒
コンタクト: 銅合金
リテンションレグ: 銅合金
△2. めっき: コンタクト: 全面Ni下地 接触部: 0.38 μm MIN金めっき
△3. めっき: コンタクト: 全面Ni下地 接触部: 0.76 μm MIN金めっき
△4. めっき: コンタクト: 全面Ni下地 接触部: 2.0 μm MINスズめっき
△5. めっき: リテンションレグとコンタクト半田付部: ニッケル下地の上に半田めっき
△6. めっき: リテンションレグとコンタクト半田付部: ニッケル下地の上にスズめっき

KEYING LOCATION	A ROW KEYING	B ROW KEYING	FINISH	製品番号 PART NO.
B ROW	X	Y	△5 △4	3-316080-5
A ROW	X	Y	△6 △3	3-316080-3
A ROW	X	Y	△6 △2	3-316080-2
B ROW	Y	Y	△6 △4	2-316080-5
A ROW	Y	Y	△6 △3	2-316080-3
A ROW	Y	Y	△6 △2	2-316080-2
B ROW	X	X	△6 △4	1-316080-5
A ROW	X	X	△6 △3	1-316080-3
A ROW	X	X	△6 △2	1-316080-2

TE Connectivity

10 POS DOUBLE ROW
HORIZONTAL HDR ASS'Y FOR DYNAMIC D-3200

WIRE RANGE: mm²(AWG) - mm²
INSULATION DIA: mm
MATERIAL: SEE NOTE 注記参照
FINISH: SEE NOTE 注記参照

NAME: 10 POS DOUBLE ROW HORIZONTAL HDR ASS'Y FOR DYNAMIC D-3200

一般公差 (GENERAL TOLERANCE): 10mm ±0.3, 10mm 3mm ±0.4, 30mm 100mm ±0.45, 角 ±0.3

SIZE: A3, LOC: J, NUMBER: C-316080

SCALE: 2-1, REV: B3, SHEET: 1 OF 1

B3	REVISED PER ECO-11-005030	RK	HMR	25MAR11
LTR	REVISION RECORD	DR	CHK	DATE

DR.	4/JUL/95	DE.	4/JUL/95
CHK.	K.IKEDA	APP.	K.IKEDA